FOR PATENT APPLICATION (JOINT OR SOLE) DECLARATION (Under 37 CFR § 1.63; with Power of Attorney) 9 10 / FROMMER LAWRENCE & HAUG LLP FIRE No.

P KOI III	
1 believe I am the original, first and and joint inventor (if plural names are listed and the invention ENTILED:	sole inventor (if only one name is listed below) or an original, first sole inventor (if only one name is listed below) of the subject matter which is claimed and for which a patent is below) of the subject matter which is claimed and for which a patent is
END-CAPPED POLYFL	UORENES, FILMS AND DEVICES BASED THEREON
the specification of which	
is seemed boroto	
X was filed on 20 April 2001 as	International Application Serial No. <u>PCT/EPD1-04522</u> ,
	(11 applicable, 3112 dates)
I hereby state that I have reviewed are the claims, as amended by any amendment refers 1 acknowledge the duty to disclose to to be material to patentability as defined in I hereby claim foreign priority benefter patent or inventor's certificate listed be inventor's certificate having a filing date be Prior Foreign Application(s) Number: Countrell	Title 37, Code of Federal Regulations, Sec. 1.56. its under Title 35, United States Code, § 119 of any foreign application(s) its under Title 35, United States Code, § 119 of any foreign application for patent or elow and have also identified below any foreign application for patent or elow and have also identified below any foreign application for patent or elow and have also identified below any foreign application for patent or elow and have also identified below any foreign application(s) Filed (Day/Month/Year): 26 April 2000 20 April 2001 X e 35, United States Code, § 120 of any United States application(s) listed ach of the claims of this application is not disclosed in the prior United the first paragraph of Title 35, United States Code § 112, I acknowledge the and Trademark Office all information known to me to be material to
Prior U.S. Application(s) [(1st add)	Clouds apprications on the contract abandoned).
I hereby appoint WILLIAM S. FROMMER of their duly appointed associate, my attorned application, to make alterations and amendmen receive the Patent, and to transact all busing therewith, and specify that all communication address:	, Registration No. 25,506, and DENNIS M. SMID, Registration No. 34,930 eys, with full power of substitution and revocation, to prosecute this ats therein, to file continuation and divisional applications thereof, to make the Patent and Trademark Office and in the Courts in connection as about the application are to be directed to the following correspondence. Direct all telephone calls to:
WILLIAM S. FROMMER , Esq.	(212) 588-0800
c/o FROMMER LAURENCE & HAUG LLP	to the attention of:
New York, New York 10151 I hereby declare that all statements information and belief are believed to be trivial ful false statements and the like so made the United States Code and that,	WILLIAM S. FROMMER i made herein of my own knowledge are true and that all statements made on ue; and further that these statements were made with the knowledge that le are punishable by fine or imprisonment, or both, under Section 1001 of such willful false statements may jeopardize the validity of the application
or any patent issued thereon.	142 Lasuala 6/12/01
Residence: Citizenship: P.O. Address:	Akin YASIDA Stuttgart, Germany Germany C/O Advanced Technology Center Stuttgart SONY International (Europe) GmbH Reinrich-Hertz-Strage 1
)	Reinrich-Hertz-Stragge 1 70327 Stuttgart REMANY Ligury Line Date: 10/12/0/

Wolfgang KNOLL

Mainz, Germany

c/o Max-Planck-Institut für Polymerforschung Ackermannweg 10 55128 Mainz GERMANY

[Similarly list additional inventors on separate page]
Post Office Address(es) of inventor(s):
[if all inventors have the same post office address]

Full name of 2nd joint inventor (if any):

Signature:

Residence:

Citizenship: P.O. Address:

Note: A post office address must be provided for each inventor.

		FLH File No. 450117-0370
	ADDITIONAL INVENTORS	
Signature: Inducas Chi	sel	Date: 12/07/2001
Full name of 3rd joint inventor (if any):	Andreas MEISEL .	Ţ.
Residence: Citizenship:	Frankfurt/Main, Germa	ny
P Address:	c/o Mex-Planck-Institut für Polyme Ackermannweg 10 55128 Mainz, GERMANY	rforschung
Signature:		Date:
Full name of 4th joint inventor (if any): Residence: Citizenship:	Tzenka MITEVA Stuttgart, Germany Germany	•
P.O. Address:	c/o Advanced Technology Center Stu SONY International (Europe) GmbH Heinrich-Hertz-Strasse 1	ittgart
· · · · · · · · · · · · · · · · · · ·	70327 Stuttgart, GERMANY	
Signature: William	<u>'</u>	Date: 49.17. 2001
Full name of 5th joint inventor (if any):	Dieter NEHER	
Residence:	Potsdam, Germany	
Citizenship: P.O. Address:	Germany c/o Max-Planck-Institut für Polyme Ackermannweg 10 55128 Mainz, GERMANY	erforschung
	•	•
Signature:	Mater Constitution	Date:
Full name of 6th Joint inventor (if any):	Heinz-Georg NOTHOFER	
Citizenship:	Stuttgart, Germany	
P.O. Address:	c/o Advanced Technology Center Stu SONY International (Europe) GmbH Heinrich-Hertz-Strasse 1	ettgart
1 Signature Rel-U SQL	70327 Stuttgart, GERMANY	Date: 19.12.2001
Full name of 7th joint inventor (if any)	Ullrich SCHERF	
Residence:	Golm, Germany	
្នាំ P.O. Address:	c/o Max-Planck-Institut für Polyme Ackermannueg 10	erforschung
: I , rating	55128 Mainz, GERMANY	
<u></u>		
		•





DECLARATION FOR PATENT APPLICATION (JOINT OR SOLE) (Under 37 CFR § 1.63; with Power of Attorney) FROMMER LAWRENCE & HAUG LLP FLH File No. 450117-03703

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

1 believe I am the original, first and sole inventor (if only one name is listed below) or an original, first
and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention ENTITLED:

END-CAPPED POLYF	LUORENES, FILMS AND DEVICES BASED THEREON			
the specification of which				
is attached hereto.				
X was filed on 20 April 2001 a	s International Application Serial No. <u>PCT/EPO1-04522</u> ,			
with amendment(s) through	(If applicable, give dates).			
the claims, as amended by any amendment refer I acknowledge the duty to disclose to to be material to patentability as defined in I hereby claim foreign priority benef for patent or inventor's certificate listed b inventor's certificate having a filing date b	o the United States Patent and Trademark Office all information known to me in Title 37, Code of Federal Regulations, Sec. 1.56. Fifts under Title 35, United States Code, § 119 of any foreign application(s) welow and have also identified below any foreign application for patent or perfore that of the application on which priority is claimed:			
Number: Count	t additional applications on separate page]: Priority Claimed: ry: F1led (Day/Month/Year): Yes No			
00108877.2 Eur				
PCT/EP01-04522 PCT	20 April 2001 X			
below and, insofar as the subject matter of e States application in the manner provided by daty to disclose to the United States Patent patentability as defined in Title 37. Code of	le 35, United States Code, § 120 of any United States application(s) listed each of the claims of this application is not disclosed in the prior United the first paragraph of Title 35, United States Code § 112, I acknowledge the and Trademark Office all information known to me to be material to Federal Regulations, Sec. 1.56, which became available between the filing of the PCT international filing date of this application:			
	tional applications on separate page):			
Appln. Ser. Number: Filed (Day/Mo	<pre>nth/Year):</pre>			
pt their duly appointed associate, my attorne application, to make alterations and amendmen receive the Patent, and to transact all busing therewith, and specify that all communication and dress:	, Registration No. <u>75,506</u> , and <u>DENNIS M. SMID</u> , Registration No. <u>34,930</u> eys, with full power of substitution and revocation, to prosecute this sts therein, to file continuation and divisional applications thereof, to ness in the Patent and Trademark Office and in the Courts in connection as about the application are to be directed to the following correspondence			
WILLIAM S. FROMMER . Esq.	Direct all telephone calls to:			
c/o FROMMER LAWRENCE & HAUG LLP 745 Fifth Avenue	(212) 588-0800 to the attention of:			
New York, New York 10151	WILLIAM S. FROMMER			
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. INVENTOR(S): Signature: Date:				
full name of sole or first inventor:	Akio YASUDA			
Residence: Citizenship:	Stuttgart, Germany Germany			
P.O. Address:	C/O Advanced Technology Center Stuttgart SONY International (Europe) GmbH Heinrich-Hertz-Strasse 1 70327 Stuttgart, GERMANY			
Signature:	Date:			
Full name of 2nd joint inventor (if any): Residence: Citizenship: P.O. Address:	Wolfgang KNOLL Mainz, Germany Germany c/o Max-Planck-Institut für Polymerforschung Ackermannweg 10 55128 Mainz, GERMANY			
[Similarly list additional inventors on sepa Post Office Address(es) of inventor(s): (if all inventors have the same post office				

Note: A post office address must be provided for each inventor.





FLH File No. 450117-03703

		MODITIONAL THACKING	•
	1. One se 10.	· 0 ·	12 1-2-12-
つし	Signature: WSECUS EUG	Sel .	(2/07/2001
$\mathcal{J}^{U^{\perp}}$	full name of 3rd joint inventor (if any):	Andr as MEISEL	101011
	Residence:		•
	Citizenship:	Frankfurt/Main, Germany Germany	
	P.O. Address:		
		c/o Max-Planck-Institut für Polymerforsch Ackermannueg 10	nung
,		55128 Mainz, GERMANY	
	× T 1/11 - 1-	SSILO HOTILE, BERFORM	
1111	Signature: Mittera	Date:	20/12/200/
HW.	Full name of 4th joint inventor (if any):	Tzenka MITEYA	
1	Residence:		
	Citizenship:	Stuttgart, Germany	
	P.O. Address:	c/o Advanced Technology Center Stuttgart	
		SONY International (Europe) GmbH	
	•	Heinrich-Hertz-Strasse 1	
		70327 Stuttgert, GERMANY.	•
	•	TUSE! STUTEGET C, GCKMANT.	•
			•
	Signature:	•	•
•	Full name of 5th joint inventor (if any):	Dieter NEHER Date:	
	Residence:	DICCCI HOILN	
	Citizenship:	Germany	• *
	P.O. Address:	c/o Max-Planck-Institut für Polymerforsch	·
		Ackermannueg 10	nung
	1. 41 / 1.	55128 Mainz, GERMANY	
1		The state of the s	
1	> Man Y Not lale		2011/21/2001
.44	Signature:		20/12/2901
. 417	Full name of 6th joint inventor (if any):	Heinz-Georg NOTHOEER	
1, 04	Residence:	Stuttgart Cormani	
	Eltizenship:	Stuttgart, Germany	•
	P.O. Address:	c/o Advanced Technology Center Stuttgart	
=		SONY International (Europe) GmbH	_
1.3	7	Heinrich-Hertz-Strasse 1	
F3			
: 23	π π	70327 Stuttgart, GERMANY	
/1		70327 Stuttgart, GERMANY	
. 21	"Signature:	70327 Stuttgart, GERMANY Date:	
(m)	Signature:	70327 Stuttgart, GERMANY	
121	Signature:	70327 Stuttgart, GERMANY Date:	
	Signature:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany	
j.	signature: #Full name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsci	hung
j.	signature: #Full name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung
i i i i i i i i i i i i i i i i i i i	Signature: Full name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsci	hung
	Signature: Full name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung
	Signature: Full name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung
	Signature: Frull name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung
	Signature: Frull name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung
	Signature: Frull name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung
	Signature: Frull name of 7th joint inventor (if any): Residence: Citizenship: P.O. Address:	70327 Stuttgart, GERMANY Ullrich SCHERF Germany c/o Max-Planck-Institut für Polymerforsch Ackermannneg 10	hung